

*A1 (concluded)*  
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micron and sub micron-scaled structures onto a plane or curved surface.--

Please replace the paragraph beginning at page 13, line 1, with the following rewritten paragraph:

*A2*  
--The material of which the soft layer 5 is made of provides a compression modulus which is at least 5 times smaller than the compression modulus of the patterned layer 2. Typically the soft layer 5 provides a Young modulus of 0.6 MPa (21Shore A) whereas the stamp material of which the patterned layer is made of, like PDMS, provides a Young modulus of about 3 MPa. Also the thickness of the soft layer 5 should be much bigger than the thickness of the stamp 2. A typical layer thickness of the soft layer 5 is about 2 mm whereas the stamp is about 200  $\mu$ m and thinner. The carrier layer 1 is made of a rigid material which is rigid in the plane of the layer, i.e. rigid in the x-y-plane but flexible perpendicular to this plane, so that the stamp device can be curved for example around the superficies of a cylinder.--

In the Claims

Please amend claim 1 as follows:

*A3*  
1. (Amended) Stamp device for printing a pattern on a surface of a substrate having a two-sided rigid carrier layer providing on it's first side a patterned layer made of a first material and being combined on it's second side with a soft layer made of a softer material than said first material,

*B*  
said carrier layer describes an x-y-plane in which said carrier layer is rigid and said carrier layer is flexible in a direction perpendicular to said x-y-plane.

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[Please amend claim 2 as follows:]

2. (Amended) Stamp device for printing a pattern on a surface of a substrate comprising:

*23 concluded*  
a two-sided rigid carrier layer providing on it's first side a patterned layer made of a first material and a contact means having at least one soft layer made of softer material than said first material for contacting the second side of said carrier layer,

*B*  
said carrier layer describes an x-y-plane in which said carrier layer is rigid and said carrier layer is flexible in a direction perpendicular to said x-y-plane.

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Please amend claim 14 as follows:

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*24*  
14. (Amended) Stamp device for printing a pattern on a surface of a substrate having a two-sided rigid carrier layer providing on it's first side a patterned layer made of a first material and being combined on it's second side with a soft layer made of a softer material than said first material,

*25*  
wherein said patterned layer provides at least one force transducer zone for monitoring a force induced load acting between said stamp and said substrate,

said force transducer zone provides a patterned structure surrounding at least an area free of structures and in said area free of structures additional structures, like linear

structures, are provided which divide said area free of structures in at least two sections,